

Ceramic Plate Series Thermoelectric Cooler

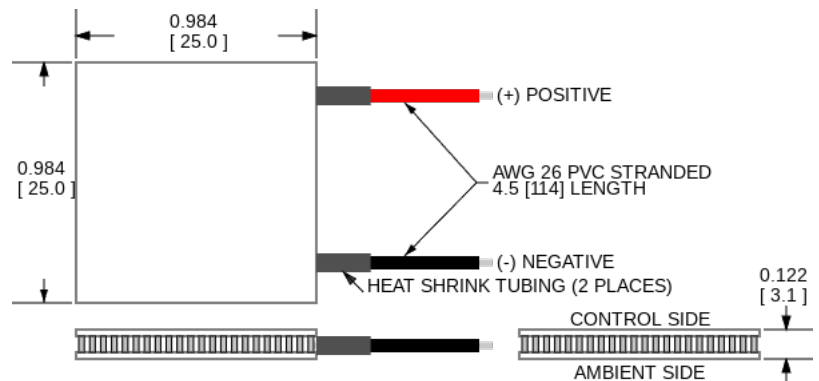
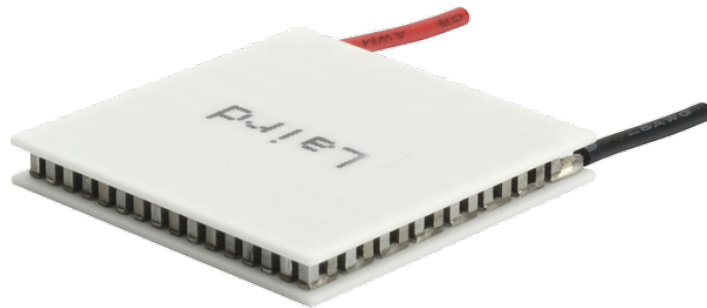
The CP08-127-05-L1-W4.5 is a high-performance and highly reliable standard Thermoelectric Cooler. Assembled with Bismuth Telluride semiconductor material and thermally conductive Aluminum Oxide ceramics. It has a maximum Q_c of 21.7 Watts when $\Delta T = 0$ and a maximum ΔT of 70.5 °C at $Q_c = 0$.

Features

- Compact geometric sizes
- DC Operation
- RoHS-compliant

Applications

- Thermoelectric Coolers for Reagent Storage
- Thermoelectric Coolers for Handheld Cosmetic Lasers
- Cooling for Centrifuges
- Peltier Cooling for Machine Vision



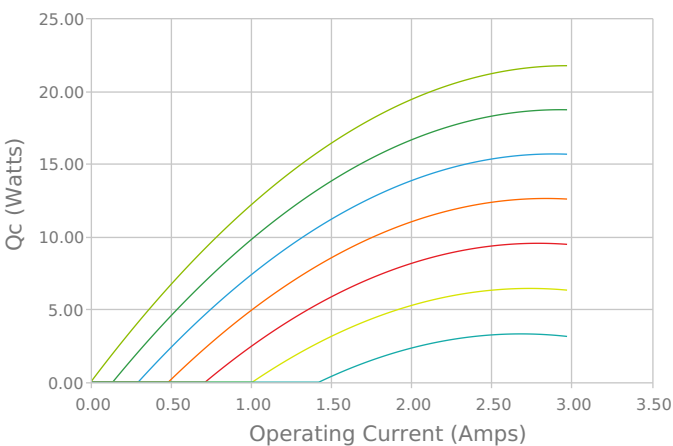
CERAMIC MATERIAL: Al_2O_3
 SOLDER CONSTRUCTION: 138°C, BiSn

INCHES [MM]

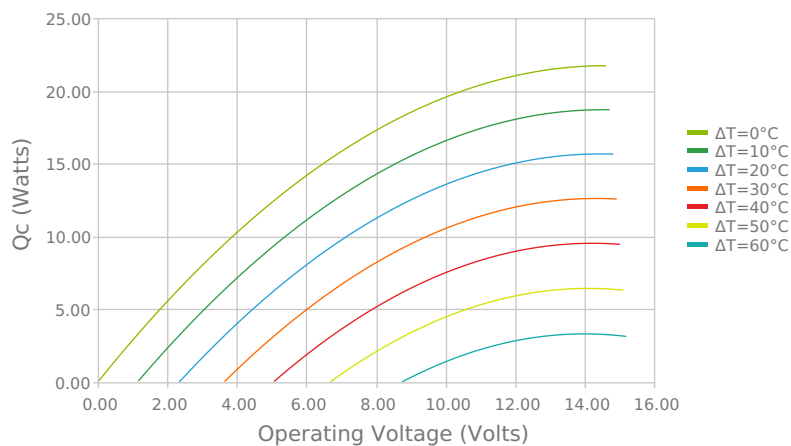
ELECTRICAL AND THERMAL PERFORMANCE

For maximum performance, be sure to orient the CONTROL side of the TEC against the application to be managed and the AMBIENT side against the heat sink or other heat rejection method. The CONTROL side is always opposite the side with lead attachments. Lead attachment is a passive heat loss and less impactful if located on the side that attaches to the heat exchanger.

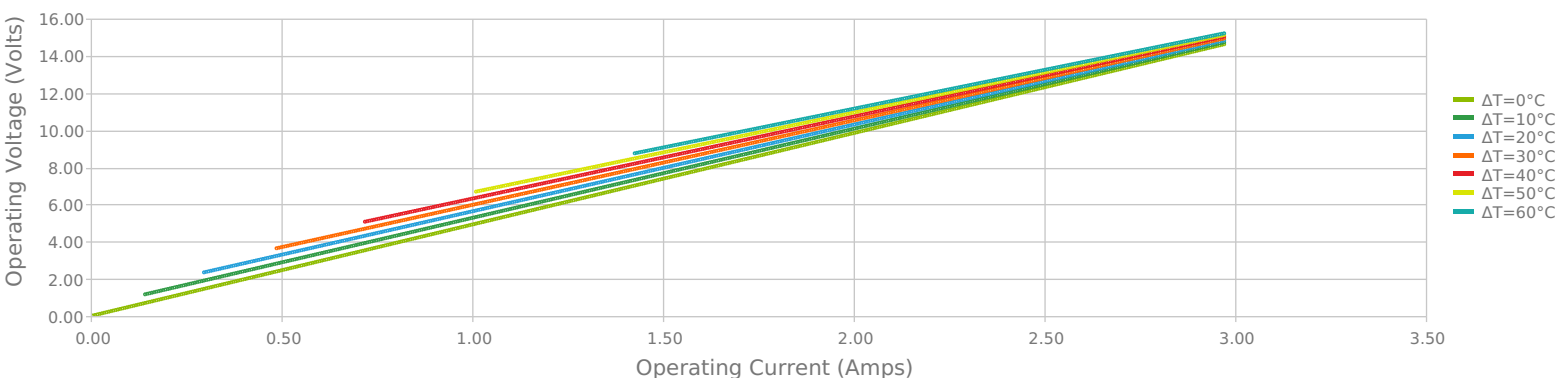
Heat Pumped at Cold Side
 $T_{hot} = 27\text{ °C}$



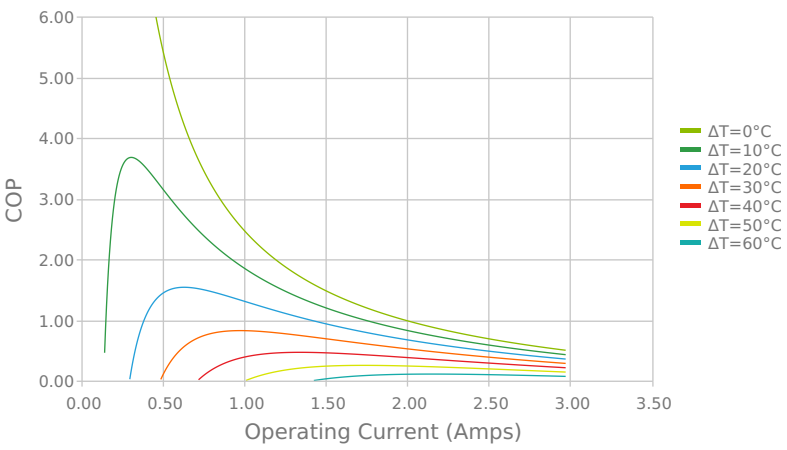
Heat Pumped at Cold Side
 $T_{hot} = 27\text{ °C}$



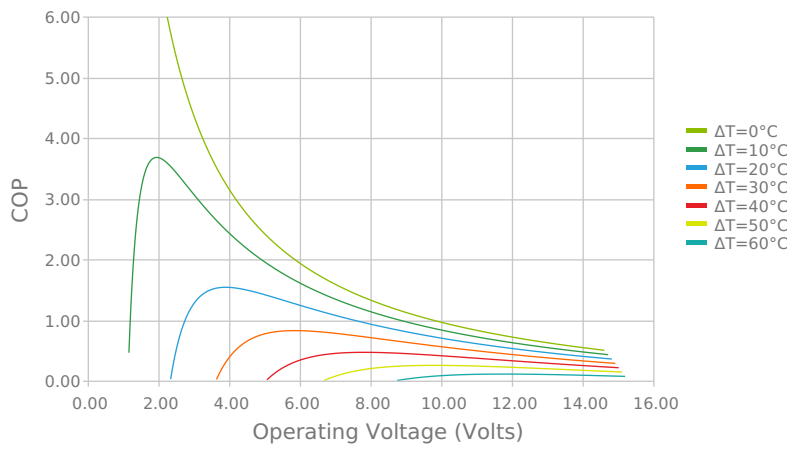
Current vs Voltage (I vs V)
 $T_{hot} = 27\text{ °C}$



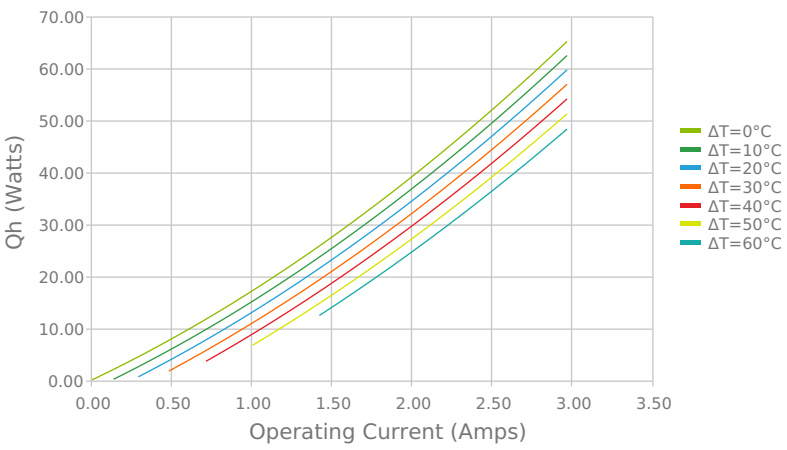
Coefficient of Performance (COP = Q_c/P_{in})
 $T_{hot} = 27\text{ }^{\circ}\text{C}$



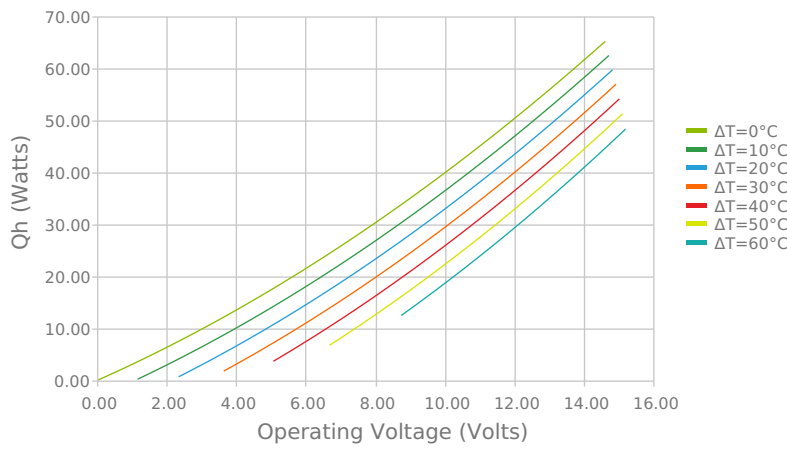
Coefficient of Performance (COP = Q_c/P_{in})
 $T_{hot} = 27\text{ }^{\circ}\text{C}$



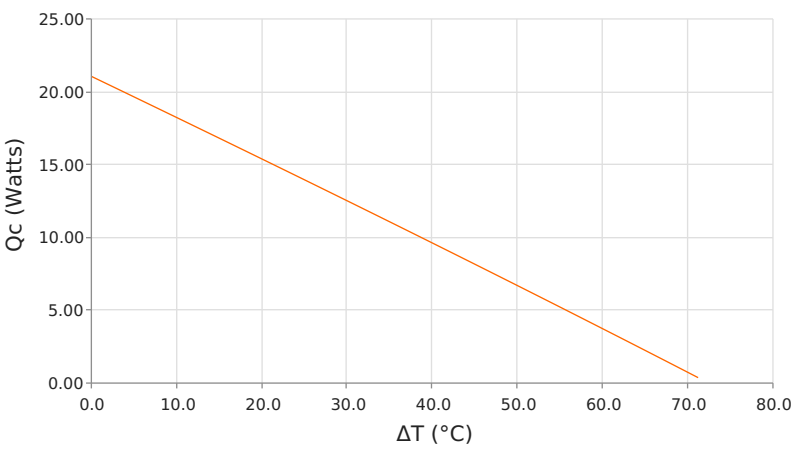
Total Heat Dissipated at Hot Side ($Q_h = Q_c + P_{in}$)
 $T_{hot} = 27\text{ }^{\circ}\text{C}$



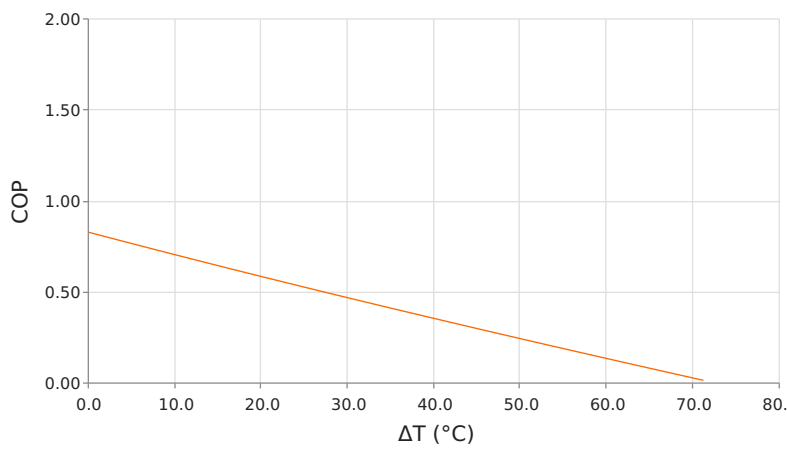
Total Heat Dissipated at Hot Side ($Q_h = Q_c + P_{in}$)
 $T_{hot} = 27\text{ }^{\circ}\text{C}$



Heat Pumped at Cold Side (Q_c)
 $T_{hot} = 35\text{ }^{\circ}\text{C}$ | $I_{operating} = 2.2\text{ Amps}$



Coefficient of Performance (COP = Q_c/P_{in})
 $T_{hot} = 35\text{ }^{\circ}\text{C}$ | $I_{operating} = 2.2\text{ Amps}$



SPECIFICATIONS

Hot Side Temperature	27.0 °C	35.0 °C	50.0 °C
Qcmax (ΔT = 0)	21.7 Watts	22.4 Watts	23.6 Watts
ΔTmax (Qc = 0)	70.5°C	73.5°C	78.8°C
Imax (I @ ΔTmax)	2.6 Amps	2.6 Amps	2.6 Amps
Vmax (V @ ΔTmax)	13.9 Volts	14.4 Volts	15.4 Volts
Module Resistance	4.92 Ohms	5.12 Ohms	5.51 Ohms
Max Operating Temperature	80 °C		
Weight	6.0 gram(s)		

FINISHING OPTIONS

Suffix	Thickness	Flatness / Parallelism	Hot Face	Cold Face	Lead Length
L1	3.099 ±0.025 mm 0.122 ± 0.0010 in	0.025 mm / 0.025 mm 0.001 in / 0.001 in	Lapped	Lapped	114.3 mm 4.50 in

SEALING OPTIONS

Suffix	Sealant	Color	Temp Range	Description
	None			No sealing specified

NOTES

1.

Max operating temperature: 80°C
2.

Do not exceed Imax or Vmax when operating module
3.

Reference assembly guidelines for recommended installation
4.

Solder tinning also available on metallized ceramics

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